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## Abstract

A thin-film assembly (1) including a substrate (2) and at least one electronic thin-film component (8) applied on the substrate by thin-film technology, wherein a base electrode (4) is provided on the substrate, on which base electrode thin-film layers (21) forming part of the thin-film component are arranged together with an upper top electrode (9); the substrate (2) is comprised of a printed circuit board (2) known per se and including an insulation-material base body (3) and a metal coating as the conductor layer (5), wherein the conductor layer (5) forms the base electrode (4) and, to this end, is smoothed at least on the location of the thin-film component (8), and wherein a contact layer (18) is applied by thin-film technology between the smoothed, optionally reinforced, conductor layer (5) and the superimposed thin-film layers (21) of the thin-film component (8), which contact layer is physically or chemically adsorbed on the surface of the base electrode (4).